

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

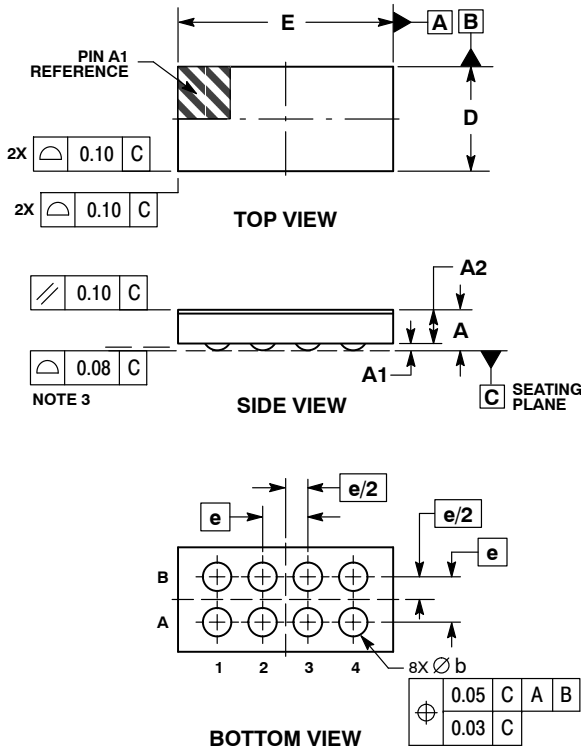
ON Semiconductor®



SCALE 4:1

WLCSP8, 1.15x2.37, 0.5P  
CASE 567JT  
ISSUE A

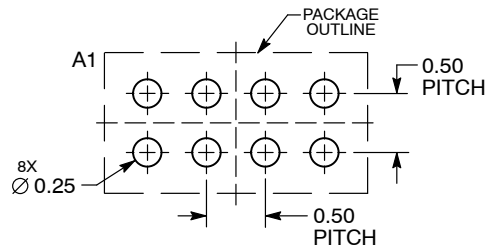
DATE 26 SEP 2014



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.35	0.45
A1	0.045	0.115
b	0.20	0.30
D	1.12	1.18
E	2.34	2.40
e	0.50 BSC	

### RECOMMENDED SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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